

numeral 220 has been corrected to 530 to avoid duplication and corresponding amendments have been made in the specification.

No new matter is introduced by these amendments and acceptance of these proposed corrections is respectfully requested.

IN THE CLAIMS

Please amend claims 1 and 14 as follows:

*B5*

1 1. (Twice Amended) An assembly for holding a substrate, the substrate having a first  
2 surface, a second surface opposite the first surface, and an outer peripheral portion, said  
3 assembly comprising:  
4       a holding body having a support surface for supporting the substrate, said holding  
5 body having an aperture for passing therethrough a gas having a first thermal conductivity;  
6 and  
7       a heat transferring seal having a first surface for frictionally engaging said second  
8 surface of said substrate, said heat transferring seal having a second surface, opposite said  
9 first surface, for frictionally engaging said support surface of said holding body, said heat  
10 transferring seal having an inner peripheral portion defining an opening for receiving the  
11 gas, wherein said heat transferring seal has a second thermal conductivity, [and a cross-  
12 section configured to transfer heat to or from the substrate uniformly] the relation between  
13 the first thermal conductivity and the second thermal conductivity being such that heat  
14 transfer between said holding body and the substrate is substantially uniform across the  
15 substrate.

*B6*

1 14. (Twice Amended) A heat transferring seal for placing in an assembly for holding a  
2 substrate, said substrate having a first surface and a second surface opposite the first surface,  
3 said assembly including a holding body having a support surface for supporting the

4 substrate, the holding body having an aperture for passing therethrough a gas having a first  
5 thermal conductivity, the heat transferring seal comprising:  
6 ~~a heat transferring seal having~~ a first surface for frictionally engaging said second  
7 surface of said substrate, said heat transferring seal having a second surface, opposite said  
8 first surface, for frictionally engaging said support surface of said holding body, said heat  
9 transferring seal having an inner peripheral portion defining an opening for receiving the  
10 gas, wherein said heat transferring seal has a second thermal conductivity, [and a cross-  
11 section configured to transfer heat to or from the substrate uniformly] the relation between  
12 the first thermal conductivity and the second thermal conductivity being such that heat  
13 transfer between said holding body and the substrate is substantially uniform across the  
14 substrate.

REMARKS

Reconsideration of this application, as amended, is respectfully requested. As indicated, the specification and drawings have been corrected to eliminate the inadvertent duplication of reference numerals to refer to different elements and to clarify that Figures 4a, 4b, 4c and 5 show different embodiments of the present invention. Reference numeral 223 has been corrected to 222 at page 7, line 10 and reference numeral 217 corrected in Figure 3. No new matter as been added and these amendments now obviate the objections set forth in the Office Action.

Claims 1 and 14 have been amended to more clearly recite the present invention. Support for these amendments may be found, for example, at p. 9, ll. 24-27. No new matter has been added.

The present claims are patentable over the cited art of record which fails to teach or suggest a heat transferring seal having the thermal conductivity properties recited in claims 1 and 14. As noted in the specification at p. 9, such a heat transferring seal provides for more than separating the outer peripheral portion of a wafer from a holding body. It also provides a medium for transferring heat, which allows for uniform heat transfer across the substrate.